

规格书编号

SPEC NO :

产品规格书

SPECIFICATION

CUSTOMER 客户: _____
PRODUCT 产品: _____ SAW RESONATOR _____
MODEL NO 型号: _____ HDR418M-T039 ±150K _____
PREPARED 编制: _____ CHECKED 审核: _____
APPROVED 批准: _____ D A T E 日期: _____ 2006-5-11 _____

客户确认 CUSTOMER RECEIVED:		
审核 CHECKED	批准 APPROVED	日期 DATE

无锡市好达电子有限公司
Shoulder Electronics Limited

更改历史记录 History Record

更改日期 Date	规格书编号 Spec. No.	产品型号 Part No.	客户产品型号 Customer No.	更改内容描述 Modify Content	备注 Remark

1. SCOPE

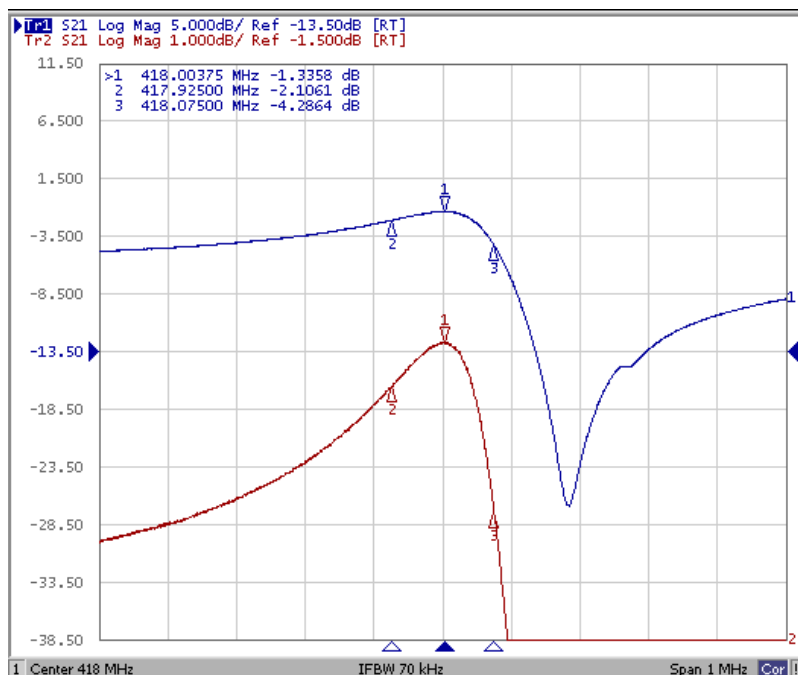
This specification shall cover the characteristics of 1-port SAW resonator with used for remote-control security.

2. ELECTRICAL SPECIFICATION

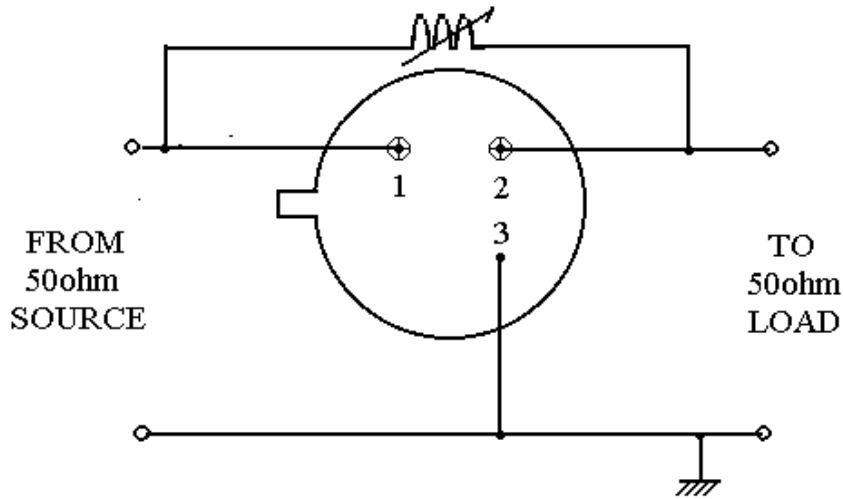
DC Voltage VDC	10V
AC Voltage Vpp	10V50Hz/60Hz
Operation temperature	-40°C to +85°C
Storage temperature	-45°C to +85°C
RF Power Dissipation	0dBm

2.2 Electronic Characteristics

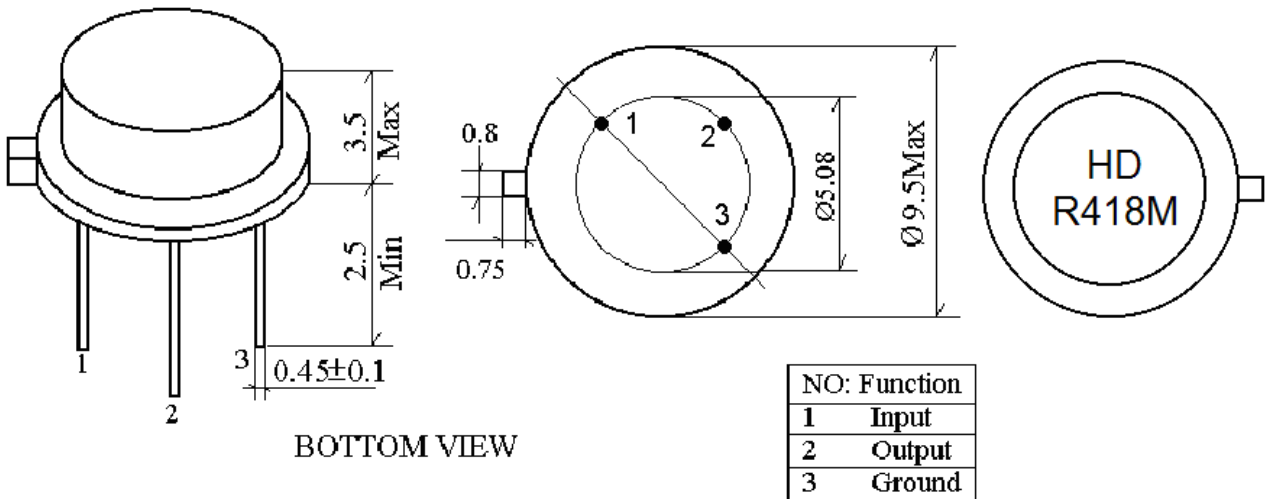
Item	Unites	Minimum	Typical	Maximum	
Center Frequency	MHz	417.850	418.000	418.150	
Insertion Loss	dB		1.5	2.5	
Quality Factor Unload Q		5000	10000		
50Ω Loaded Q		800	1200		
Temperature	Turnover Temperature	°C	10	25	40
Stability	Freq.temp.Coefficient	ppm/°C ²	0.032		
Frequency Aging	ppm/yr		<±10		
DC. Insulation Resistance	MΩ	1.0			
RF Equivalent RLC Model	Motional Resistance R1	Ω	21	26	
	Motional Inductance L1	μH	81.761		
	Motional Capacitance C1	fF	1.7731		
Transducer Static Capacitance	pF		1.9		



3. TEST CIRCUIT



4. DIMENSION



5. ENVIRONMENTAL CHARACTERISTICS

5-1 High temperature exposure

Subject the device to +85°C for 16 hours. Then release the resonator into the room conditions for 24 hours prior to the measurement. It shall fulfill the specifications in 2.2.

5-2 Low temperature exposure

Subject the device to -40°C for 16 hours. Then release the device into the room conditions for 24 hours prior to the measurement. It shall fulfill the specifications in 2.2.

5-3 Temperature cycling

Subject the device to a low temperature of -40°C for 30 minutes. Following by a high temperature of +85°C for 30 Minutes. Then release the device into the room conditions for 24 hours prior to the measurement. It shall meet the specifications in 2.2.

5-4 Resistance to solder heat

Dip the device terminals no closer than 1.5mm into the solder bath at $260^{\circ}\text{C} \pm 10^{\circ}\text{C}$ for 10 ± 1 sec. Then release the device into the room conditions for 4 hours. The device shall meet the specifications in 2.2.

5-5 Solderability

Subject the device terminals into the solder bath at $245^{\circ}\text{C} \pm 5^{\circ}\text{C}$ for 5s, More than 95% area of the terminals must be covered with new solder. It shall meet the specifications in 2.2.

5-6 Mechanical shock

Drop the device randomly onto the concrete floor from the height of 1m 3 times. the device shall fulfill the specifications in 2.2.

5-7 Vibration

Subject the device to the vibration for 1 hour each in x,y and z axes with the amplitude of 1.5 mm at 10 to 55 Hz. The device shall fulfill the specifications in 2.2.

6. REMARK

6.1 Static voltage

Static voltage between signal load & ground may cause deterioration & destruction of the component. Please avoid static voltage.

6.2 Ultrasonic cleaning

Ultrasonic vibration may cause deterioration & destruction of the component. Please avoid ultrasonic cleaning

6.3 Soldering

Only leads of component may be soldered. Please avoid soldering another part of component.